

PTO/SB/08A (02-03)

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INFORMATION DISCLOSURE STATEMENT BY APPLICANT

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Complete if Known

Application Number	10/091,262
Filing Date	3/05/2002
First Named Inventor	Stewart, Steven L.
Art Unit	1771
Examiner Name	
Attorney Docket Number	US.01.012

Sheet	1	of
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U. S. PATENT DOCUMENTS

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FOREIGN PATENT DOCUMENTS

Examiner Initials*	Cite No.†	Foreign Patent Document		Publication Date	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages Or Relevant Figures Appear	†
		Country Code* Number* Kind Code* (if known)		MM-DD-YYYY			
VSC		EP	0729182A	08-28-1996	Matsushita Electric Inc		
		DE	19822470A	12-09-1999	Liton Precision Product		
		JP	08250835A	09-27-1996	NEC Corp		
		JP	10335527A	12-18-1998	NEC Corp		
		JP	03036788A	02-18-1991	Murata Mfg Co Ltd		
		JP	04249307 A	09-04-1992	Nippon Chemicon Corp		

Examiner Signature	<i>Viggo Oluf</i>	Date Considered	12/3/03
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Attorney Docket Number	US 01.012

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Cited References)ATTY. DOCKET NO.
USA.01.012SERIAL NO.
10/091262LIST OF INFORMATION PROVIDED
BY APPLICANT

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APPLICANT
STEWART, et alFILING DATE
March 5, 2002GROUP
Unknown

REFERENCE CITATION

U.S. PATENT DOCUMENTS

Examiner Initial		Document No.	Date*	Patentee	Date* Cited in Foreign Patent Office
VLC	AA	5,930,889	8/3/1999	Klein	
	AB	6084781	7/4/2000	Klein	
	AC	6238223	5/29/2001	Cobbley	
	AD	5061549	10/29/1991	Shores	
	AE	5372883	12/13/1994	Shores	
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	AG	6265776	7/24/2001	Gilleo	

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	Document No.	Country	Date*	Date* Cited in Foreign P.O.	English Translation Yes	No
FA						
FB						

OTHER PUBLICATIONS (AUTHOR, TITLE, DATE*, PLACE OF PUBLICATION, PERTINENT PAGES)

		Date* Cited in Foreign P.O.	English Translation Yes	No
PA	Adamson, S.J., "CSP and flip chip underfill," Advanced Packaging, June 2001, pp. 37-44.			
PB	Johnson, Zane, "BGA Underfills" Advanced Packaging, December 2001, pp. 29-33			
PC	Alpha Microelectronic: Staystik Adhesive for Mag Heads, [internet] Retrieved on December 19, 2001, URL: www.us-tech.com/april99/prods/cmp/cmp016.htm			
PD	Center for Advanced Vehicle Electronics, "Ball Grid Array Reliability" [Internet] Retrieved on January 8, 2002, URL: www.eng.auburn.edu/departement/ee/cave/bgareliability.html			
PE	Brofman, P.J., "Effect of Underfill Properties on Flip Chip Plastic BGA (FC-PBGA) Reliability," IPC, Session P-MT1/5-(1-5); Presented at Apex 2000, March 14-16, 2000; Long Beach Convention Center, Long Beach, CA			

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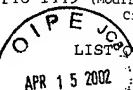
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U.S. PATENT DOCUMENTS

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	AJ	5401536	3/28/1995	Shores	

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	PF	Adamson, Steven J., "When to Underfill Chip Scale Packages, Design Consideration for Portable Electronic Applications," IPC, Session P-AD2/2-(1-8); Presented at Apex 2000, March 14-16, Long Beach Convention Center			
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	PH	Yaeger, E., "Beyond Flip-Chip, Underfills Enhance CSP Reliability," Chip Scale Review, March 2001, pp. 61-66			
	PI	Katze, D., "Evaluations of No-Flow Fluxing Underfills with BGA, CSP and Flip Chip on Board Assemblies," IPC, Session P-MT1/2-(1-7), Presented at Apex 2000, Long Beach Convention Center			
	PJ	Gilleo, K., "Thermoplastic Die Attach Adhesive for Today's Packaging Challenges," [internet] URL: http://www.cooksonsemi.com/tech_art/staystik.htm			
	PK	Hannan, N., "Critical Aspects of Reworkable Underfills for Portable Consumer Products," 2001 Electronic Components and Technology Conference, 2001 IEEE, pp 181-187			
	PL	Chapter C: Conductive Polymers, Level 1: Introduction [internet], last updated on 2000-09-07; URL: http://extra.ivf.se/ngl/C-polymerBonding/ChapterC.htm			
	PM	Kristiansen, H., "Adhesives in Electronics," Chalmers Tekniska Hogskola, SINTEF Microelectronics; Presented at International Microelectronics and Packaging Society, Flipchip Technology Workshop, June 18-20, 2001			
	PN	Tong, Q., "Novel Fast Cure and Reworkable Underfill Materials," 1999 Electronic Components and Technology Conference, 0-7803-5234-3/99, 1999 IEEE, pp.			

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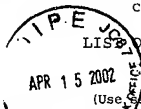
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Examiner Initial	Document No.	Date*	Patentee	Date* Cited in Foreign Patent Office

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				Yes	No
USC	PO	Nguyen, L., "Reworkable Flip Chip Underfill-Materials and Processes," Proc. IMAPS International Symposium on Microelectronics, pp. 707-713 (1998).	.		
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	PR	Thorpe, R., "Low Cost Flip Chip Processing Utilizing No Flow Underfill Materials," Presented at Apex 2000, March 14-16, 2000; Long Beach Convention Center; Session P-AP3/3-(1-8)	.		
	PS	Hackett, S., "A No-flow Underfill With Excellent Reliability Performance," IMAPS Flip Chip 2001 Austin, Texas June 18 - 19, 2001	.		
	PT	Suzuki, O., "Research on the Development of Advanced Non Conductive Paste (ANCP), Imaps Conference on Flip Chip Technology in Austin, Texas; June 18-19, 2001	.		
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STEWART, et alFILING DATE
March 5, 2002GROUP
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OTHER PUBLICATIONS (AUTHOR, TITLE, DATE*, PLACE OF PUBLICATION, PERTINENT PAGES)

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				Yes	No
VSC	PX	The National Technology Roadmap for Electronic Interconnections, Part C-Section 1-Package Style and Physical Attributes, Roadmap 2000/2001; C1-6	.		
	PY	The National Technology Roadmap for Electronic Interconnections, Part D-Section 1-Organic Interconnecting Structures, Roadmap 2000/2001; D1-15	.		
	PZ	Goyal, S, "Role of Shock Response Spectrum in Electronic Product Suspension Design," The International Journal of Microcircuits and Electronic Packaging, Volume 23, Number 2, Second Quarter 2000, pp 182-190	.		
	PAA	Yamaji, Y., "A proposal: the Assessing Method of the CSP's Mechanical Reliability on Board," The International Journal of Microcircuits and Electronic Packaging, Volume 23, Number 1, First Quarter 2000, pp 138-145	.		
	PBB	Goyal, S, "Methods for Realistic Drop-Testing," The International Journal of Microcircuits and Electronic Packaging, Volume 23, Number 1, First Quarter 2000, pp. 45-52	.		
	PCC	Xu, K., "A General Purpose Adhesive for Microelectronic Devices," The International Journal of Microcircuits and Electronic Packaging, Volume 23, Number 1, First Quarter 2000, pp. 78-84	.		
	PDD	Seppala, A, "Flip Chip Joining on GR-4 Substrate Using ACPs," The International Journal of Microcircuits and Electronic Packaging, Volume 24, Number 2, Second Quarter 2001, pp. 148-159	.		
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V3C	PEE	Gilleo, K., "New Generation Underfills Power The 2 nd Flip Chip Revolution," [internet] URL: http://www.cooksonsemi.com/tech_art/polysolder.htm		
	PFF	Hung, S.C., "Board Level Reliability of Chip Scale Packages," The International Journal of Microcircuits and Electronic Packaging, Volume 23, Number 1, First Quarter 2000, pp. 118-130		
	PGG	Gilleo, K., "Transforming Flip Chip into CSP with Reworkable Wafer-Level Underfill," [internet] URL: http://www.cooksonsemi.com/tech_art/staychip.htm		
	PHH	Gilleo, K., "The Ultimate Flip Chip-Integrated Flux/Underfill," [internet] URL: http://www.cooksonsemi.com/tech_art/staychip.htm		
	PII	Preveti, M., "No Flow Underfill Reliability is Here," [internet] URL: http://www.cooksonsemi.com/tech_art/staychip.htm		
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	PKK	Harper, P., "Thermoplastic Die Attach For Hermetic Packaging," The International Journal of Microelectronics and Electronic Packaging, Vol. 17, No. 4, Fourth Quarter, 1994, pp		
✓	PLL	Gilleo, K., "Molded Underfill for Flip Chip in Package," [internet] June, 2000; URL: http://www.cooksonsemi.com/tech_art/staychip.htm		

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